

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC2301xxxxMR-G

Typical Mass: 16 mg

| Part name | Weight(mg) | Material name | Ratio(ppm) | CAS number |
|--------------|------------|-----------------|------------|------------|
| Silicon chip | 0.379 | Silicon | 23700 | 7440-21-3 |
| | - | Arsenic | 1 | 7440-38-2 |
| Leadframe | 5.503 | Copper | 343900 | 7440-50-8 |
| | 0.022 | Tin | 1400 | 7440-31-5 |
| | 0.021 | Zinc | 1300 | 7440-66-6 |
| | 0.024 | Chromium | 1500 | 7440-47-3 |
| | 0.325 | Silver | 20300 | 7440-22-4 |
| | Die attach | 0.049 | Silver | 3000 |
| | 0.009 | Epoxy | 600 | — |
| Bonding wire | 0.060 | Gold | 3800 | 7440-57-5 |
| Resin | 7.789 | Silica | 486800 | 60676-86-0 |
| | 0.648 | Epoxy Resin | 40500 | — |
| | 0.518 | Phenol Resin | 32400 | — |
| | 0.255 | Metal Hydroxide | 15900 | — |
| Plating | 0.400 | Tin | 25000 | 7440-31-5 |

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."